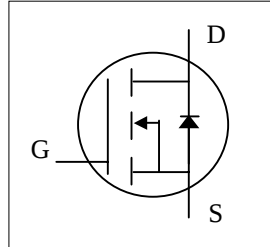
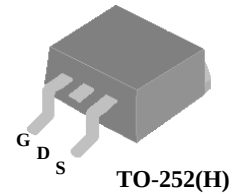


- ▼ 100% R_g & UIS Test
- ▼ Low t_{rr} / Q_{rr}
- ▼ Simple Drive Requirement
- ▼ RoHS Compliant & Halogen-Free



BV_{DSS}	600V
$R_{DS(ON)}$	0.2Ω
I_D^6	16.6A



Description

XP60SC200D series are innovated design and silicon process technology to achieve the lowest possible on-resistance and fast switching performance. It provides the designer with an extreme efficient device for use in a wide range of power applications.

The TO-252 package is widely preferred for commercial-industrial surface mount applications and suited for low voltage applications such as DC/DC converters.

Absolute Maximum Ratings@ $T_j=25^\circ\text{C}$ (unless otherwise specified)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	600	V
V_{GS}	Gate-Source Voltage	± 20	V
V_{GS}	Gate-Source Voltage, AC ($f > 1\text{Hz}$)	± 30	V
$I_D@T_C=25^\circ\text{C}$	Drain Current, V_{GS} @ $10V^6$	16.6	A
$I_D@T_C=100^\circ\text{C}$	Drain Current, V_{GS} @ $10V^6$	10.5	A
I_{DM}	Pulsed Drain Current ¹	40	A
dv/dt	MOSFET dv/dt Ruggedness ($V_{DS} = 0 \dots 480V$)	40	V/ns
$P_D@T_C=25^\circ\text{C}$	Total Power Dissipation	104	W
$P_D@T_A=25^\circ\text{C}$	Total Power Dissipation ⁵	2	W
E_{AS}	Single Pulse Avalanche Energy ³	50	mJ
dv/dt	Peak Diode Recovery dv/dt^4	15	V/ns
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ\text{C}$

Thermal Data

Symbol	Parameter	Value	Units
R_{thj-c}	Maximum Thermal Resistance, Junction-case	1.2	$^\circ\text{C}/\text{W}$
R_{thj-a}	Maximum Thermal Resistance, Junction-ambient (PCB mount) ⁵	62.5	$^\circ\text{C}/\text{W}$

Electrical Characteristics@T_j=25°C(unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =1mA	600	-	-	V
R _{DS(ON)}	Static Drain-Source On-Resistance ²	V _{GS} =10V, I _D =5.5A	-	-	0.2	Ω
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250uA	2.5	-	4.5	V
g _{fs}	Forward Transconductance	V _{DS} =10V, I _D =6.2A	-	10	-	S
I _{DSS}	Drain-Source Leakage Current	V _{DS} =480V, V _{GS} =0V	-	-	100	uA
I _{GSS}	Gate-Source Leakage	V _{GS} =±20V, V _{DS} =0V	-	-	±1	uA
Q _g	Total Gate Charge	I _D =7.5A	-	30	48	nC
Q _{gs}	Gate-Source Charge	V _{DS} =480V	-	10	-	nC
Q _{gd}	Gate-Drain ("Miller") Charge	V _{GS} =10V	-	13	-	nC
t _{d(on)}	Turn-on Delay Time	V _{DD} =300V	-	14	-	ns
t _r	Rise Time	I _D =7.5A	-	21	-	ns
t _{d(off)}	Turn-off Delay Time	R _G =3.3Ω	-	36	-	ns
t _f	Fall Time	V _{GS} =10V	-	8	-	ns
C _{iss}	Input Capacitance	V _{GS} =0V	-	1200	1920	pF
C _{oss}	Output Capacitance	V _{DS} =100V	-	55	-	pF
C _{rss}	Reverse Transfer Capacitance	f=1.0MHz	-	20	-	pF
R _g	Gate Resistance	f=1.0MHz	-	5	10	Ω

Source-Drain Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V _{SD}	Forward On Voltage ²	I _S =5.5A, V _{GS} =0V	-	0.8	1.5	V
t _{rr}	Reverse Recovery Time	I _S =7.5A, V _{GS} =0V	-	155	-	ns
Q _{rr}	Reverse Recovery Charge	di/dt=100A/μs	-	1.2	-	uC

Notes:

- 1.Pulse width limited by max. junction temperature.
- 2.Pulse test
- 3.Starting T_j=25°C , V_{DD}=90V , L=100mH , R_G=25Ω , V_{GS}=10V
- 4.I_{SD} ≤ I_D, V_{DD} ≤ BV_{DSS}, starting T_j = 25°C
- 5.Surface mounted on 1 in² copper pad of FR4 board
- 6.Limited by max. junction temperature. Maximum duty cycle D=0.75

THIS PRODUCT IS SENSITIVE TO ELECTROSTATIC DISCHARGE, PLEASE HANDLE WITH CAUTION.

USE OF THIS PRODUCT AS A CRITICAL COMPONENT IN LIFE SUPPORT, AUTOMOTIVE OR OTHER SIMILAR SYSTEMS IS NOT AUTHORIZED.

XSEMI DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS.

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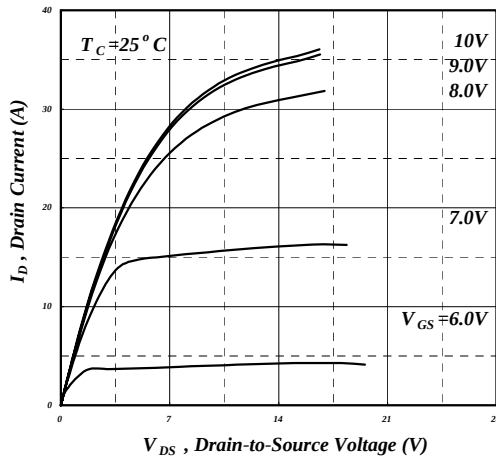


Fig 1. Typical Output Characteristics

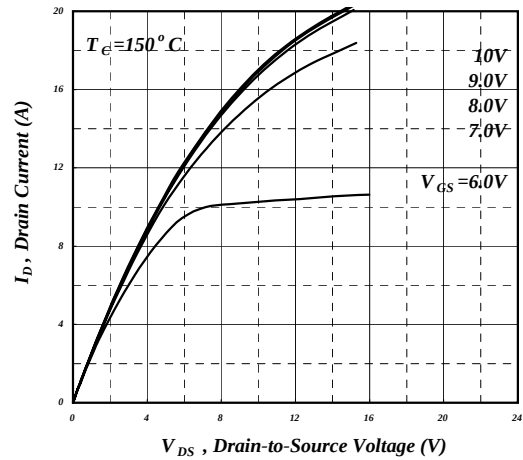


Fig 2. Typical Output Characteristics

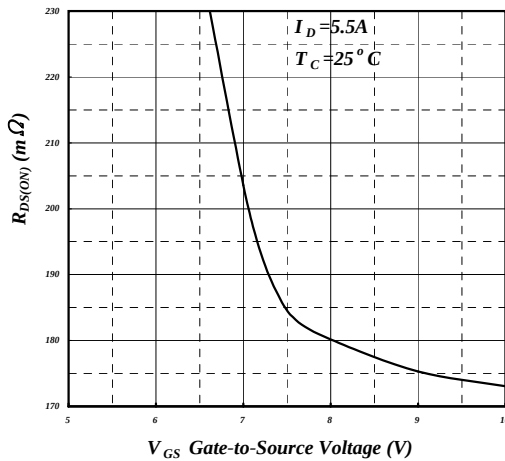
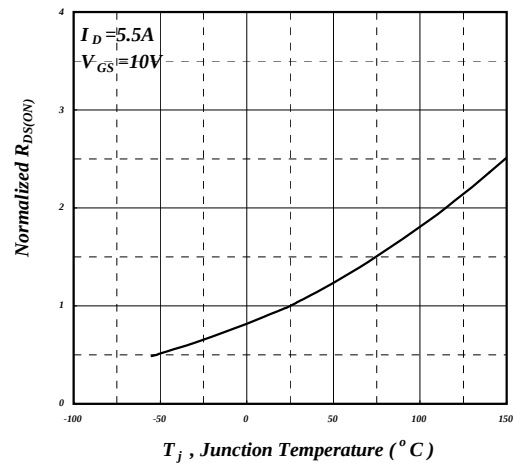
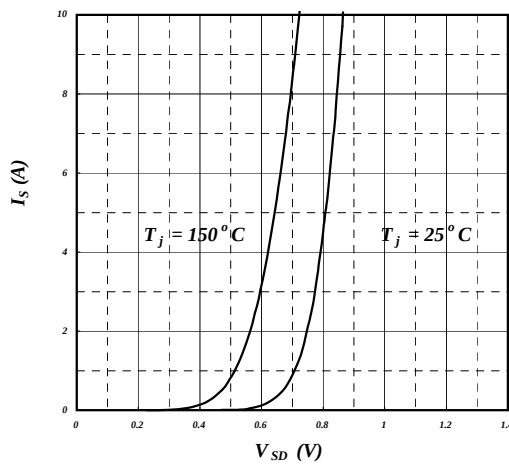


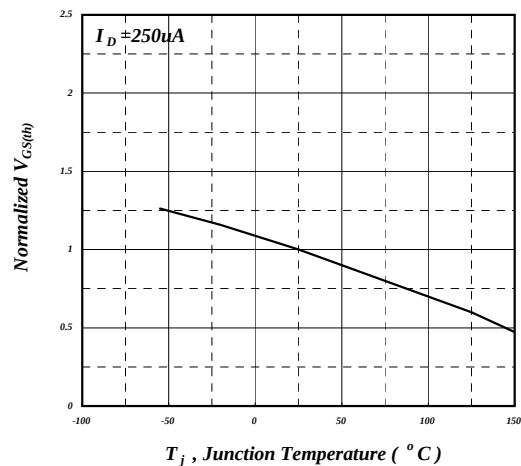
Fig 3. On-Resistance v.s. Gate Voltage



**Fig 4. Normalized On-Resistance
v.s. Junction Temperature**



**Fig 5. Forward Characteristic of
Reverse Diode**



**Fig 6. Gate Threshold Voltage v.s.
Junction Temperature**

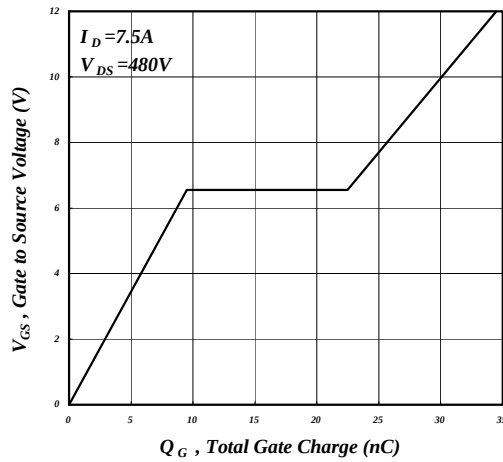


Fig 7. Gate Charge Characteristics

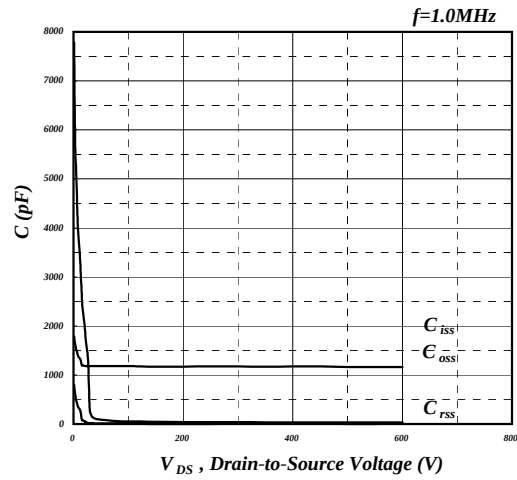


Fig 8. Typical Capacitance Characteristics

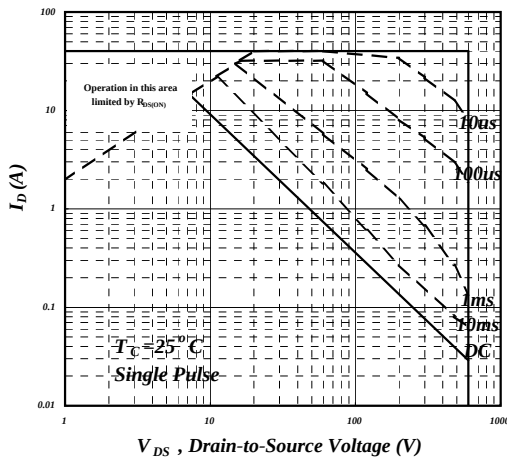


Fig 9. Maximum Safe Operating Area

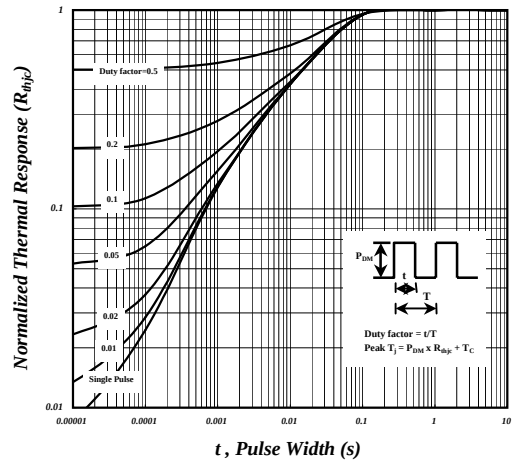


Fig10. Effective Transient Thermal Impedance

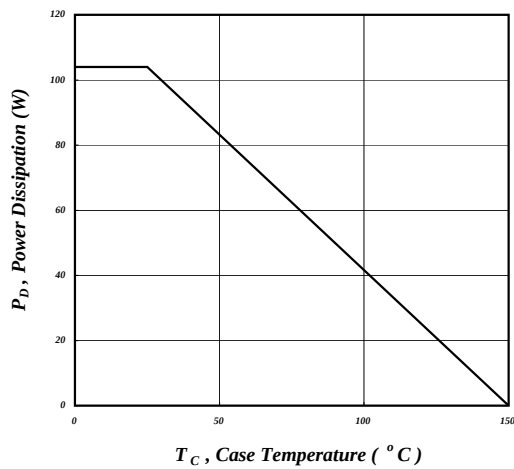


Fig 11. Total Power Dissipation

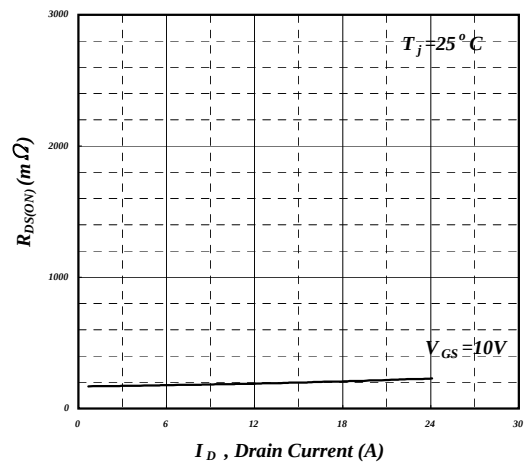
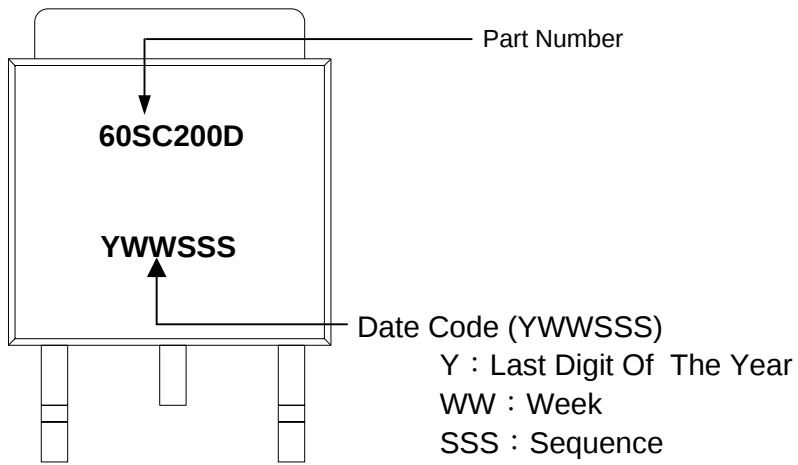
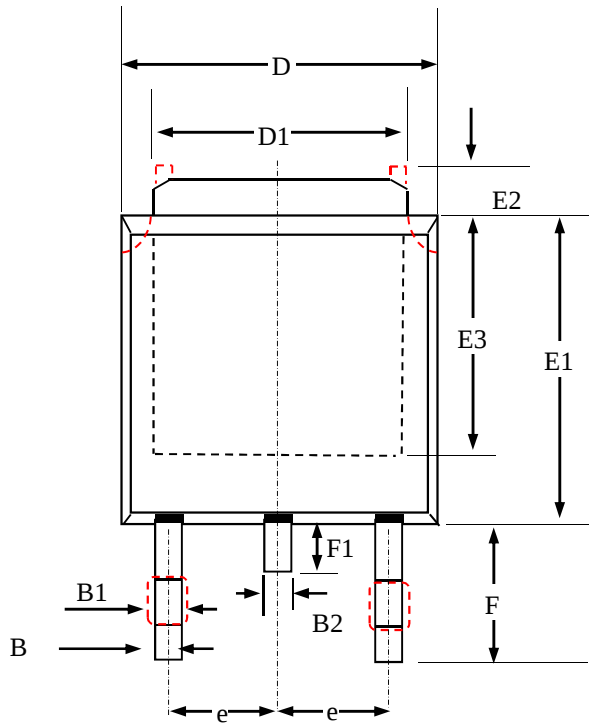


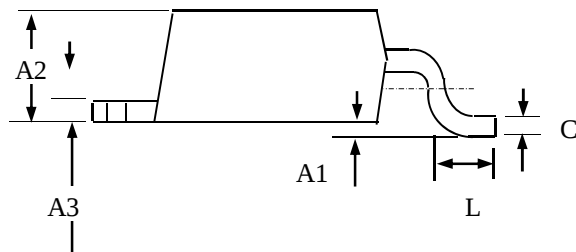
Fig 12. Typ. Drain-Source on State Resistance

MARKING INFORMATION

Package Outline : TO-252



SYMBOLS	Millimeters		
	MIN	NOM	MAX
A2	2.18	2.30	2.40
A3	0.40	0.50	0.65
B	0.40	0.70	1.00
B1	0.50	0.85	1.20
D	6.00	6.50	6.80
D1	4.80	5.35	5.90
E3	4.00 (ref.)		
F	2.00	2.63	3.05
F1	0.50	0.85	1.20
E1	5.00	5.70	6.30
E2	0.50	1.10	1.80
e	2.3 (ref)		
C	0.35	0.525	0.70
A1	0.00	—	0.25
B2	—	—	1.25
L	0.90	1.34	1.78



- 1.All Dimensions Are in Millimeters.
- 2.Dimension Does Not Include Mold Protrusions.
3. Thermal PAD, Body and Pin contour is for reference, it may has little difference by option.

TO-252 FOOTPRINT :

